

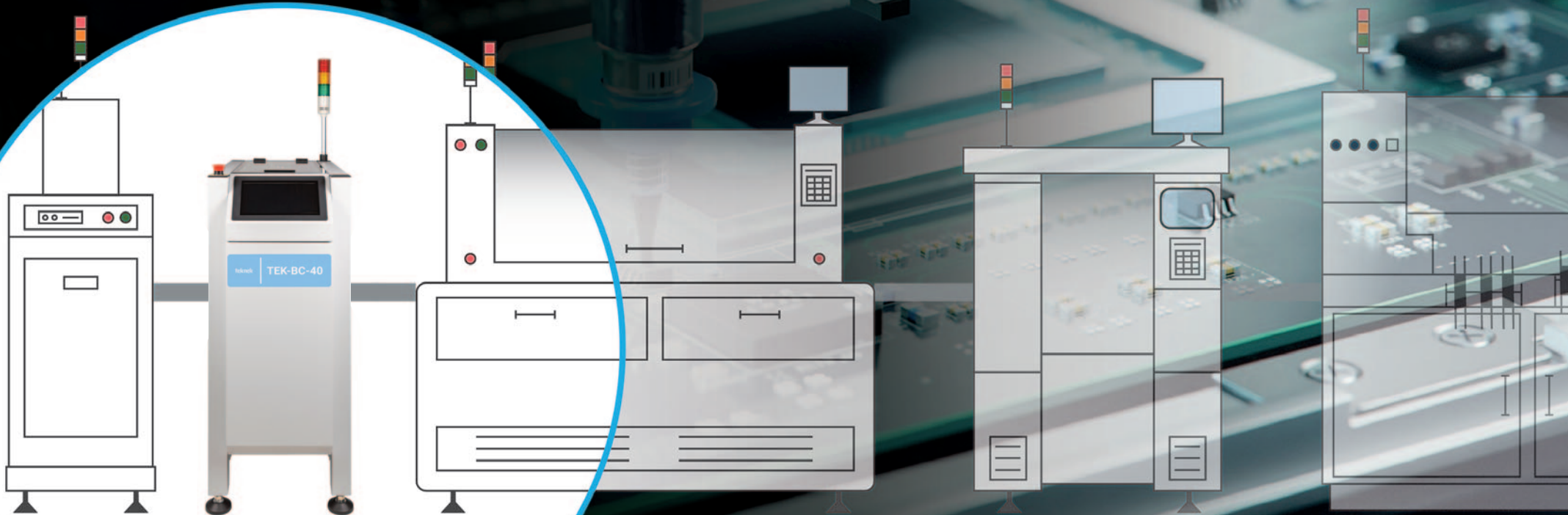
teknek

An ITW Company

TEK-BC-40

INLINE BOARD CLEANER

Contamination control at the start of the line



**Bare Board Cleaner,
Tek-BC Range**

Screen Printer

Solder Paste
Inspection (SPI)

Chip Placer

Engineered for performance & reliability

- Remove FOD
- Reduce defects
- Increase yields

The Tek-BC 40 is Teknek's latest in line board cleaner designed for the electronic assembly industry.

It removes metallic and non-metallic particulate contamination and static from bare boards before they enter the solder screen printer including debris created by a laser marker.

Teknek's innovative low static, precision touch technology removes contamination at crucial early junctures in the SMT process.

It's better at removing metallic and non-metallic particles from 5mm to 20 nanometer.

Purpose engineered for effective contamination control in advanced electronics assembly, the platform complies with IPC/JEDEC strain rate requirements. and ANSI ESD s20.20.

You're in good company, trusted by globally leading Tier 1 producers.



Why your process needs a bare board cleaner

- ✓ Removes FOD
- ✓ Lowers static
- ✓ Improves solder reliability
- ✓ Reduces faults at 3D SPI
- ✓ Reduces stencil blockages
- ✓ Increases yields
- ✓ Reduces waste & need for rework
- ✓ Improves performance
- ✓ Reduces risk of in-field failure

“By prioritizing FOD prevention initiatives and leveraging innovative cleaning solutions, the SMT and PCBA sector can uphold quality standards, enhance operational efficiency, and deliver reliable electronic products to meet market demands.”

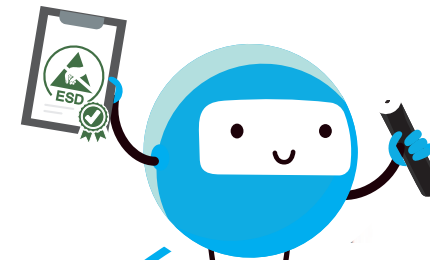
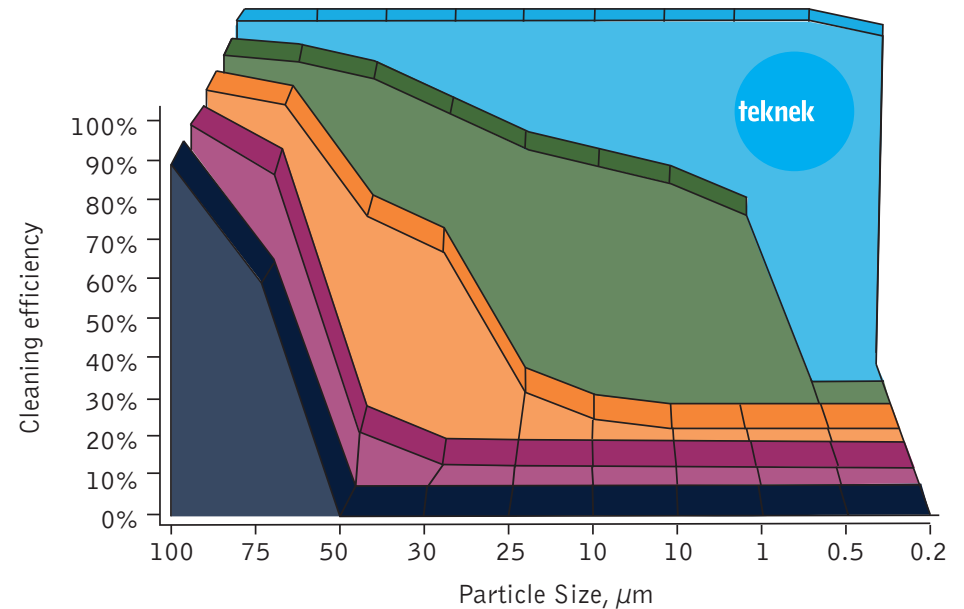
Contact cleaning best for particle removal

By incorporating Teknek Tek-BC board cleaners into manufacturing processes, companies can enhance component placement accuracy, minimize soldering defects, and improve overall product reliability.

Teknek board cleaners utilize innovative contact cleaning rollers that effectively capture and remove particles from surfaces without leaving residues or damaging sensitive components. Teknek board cleaning systems provide precision touch and guaranteed low static cleaning.

Efficiency of different cleaning methods

- Teknek Contact Clean Machine
- Ultrasonic
- Brush & Vac
- High Velocity Vacuum
- Air knife



Tekkie fact:

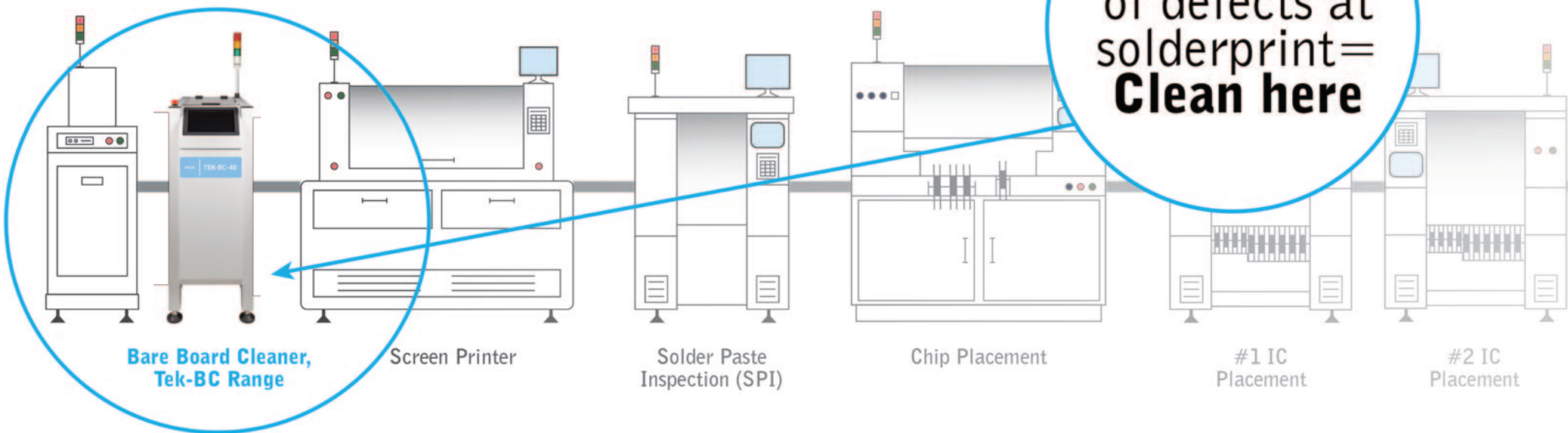
Only Teknek provides 98% cleaning efficiency for particles from 20 nanometer to 30 micrometer!

This industry leading bare board cleaner comes with 10 year warranty on belts.

Fully compliant with ANSI ESD s20.2, Teknek Tek-BC board cleaners are designed to address the specific cleanliness requirements of electronic assemblies, ensuring compliance with industry standards and specifications.

By proactively integrating Teknek board cleaners into production lines, manufacturers can mitigate FOD risks and enhance the quality and performance of electronic devices.

Over 60% of defects at solderprint = **Clean here**



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Bare Board Cleaner, Tek-BC Range

Screen Printer

Solder Paste Inspection (SPI)

Chip Placement

#1 IC Placement

#2 IC Placement

Surface mount devices

01005 0.4 x 0.2mm	0805 2.0 x 1.25mm
0201 0.6 x 0.3mm	1008 2.5 x 2.0mm
0402 1.0 x 0.5mm	1206 3.2 x 1.6mm
0603 1.6 x 0.8mm	1210 3.2 x 2.5mm

Tekkie fact:

Miniaturisation continues, and smaller components make even tiny particles increasingly problematic.

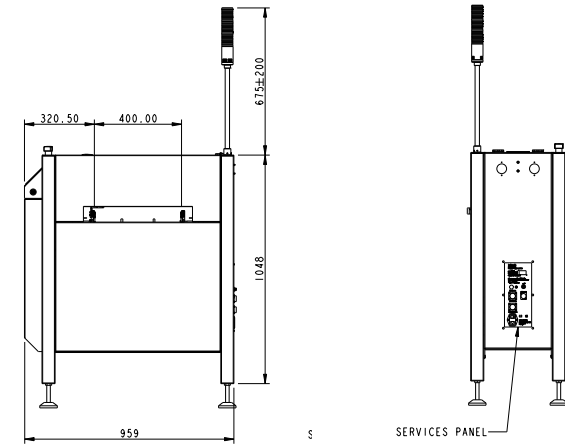
Only certified low static board cleaner to conform with global standards



Product Specification

Product	Single Side – Inline Board Cleaner
Pre-Cleaner	Brush & Vacuum modual "TOP Only"
Anti-Static	24vDC Air Assist Bar
Cleaning Width	40-400mm
Operating Mode	Clean / By-Pass
Configuration	Fixed Front Rail – L-R or R-L Flow
Cleaning Rollers	GNT – Nanoclean
Adhesive Roll	GAR – AREF
Process Speed	2-22m / min
Communication**	SMEMA / IPC XFC / Hermes
Pass Height	900 ± 50mm
Mains Power	100-240V AC
Air Supply	5-7 bar "Oil Free Air"

Note: Low Static Cleaning, ESD Compliant requires GNT & GAR. **SMEMA Cables Supplied



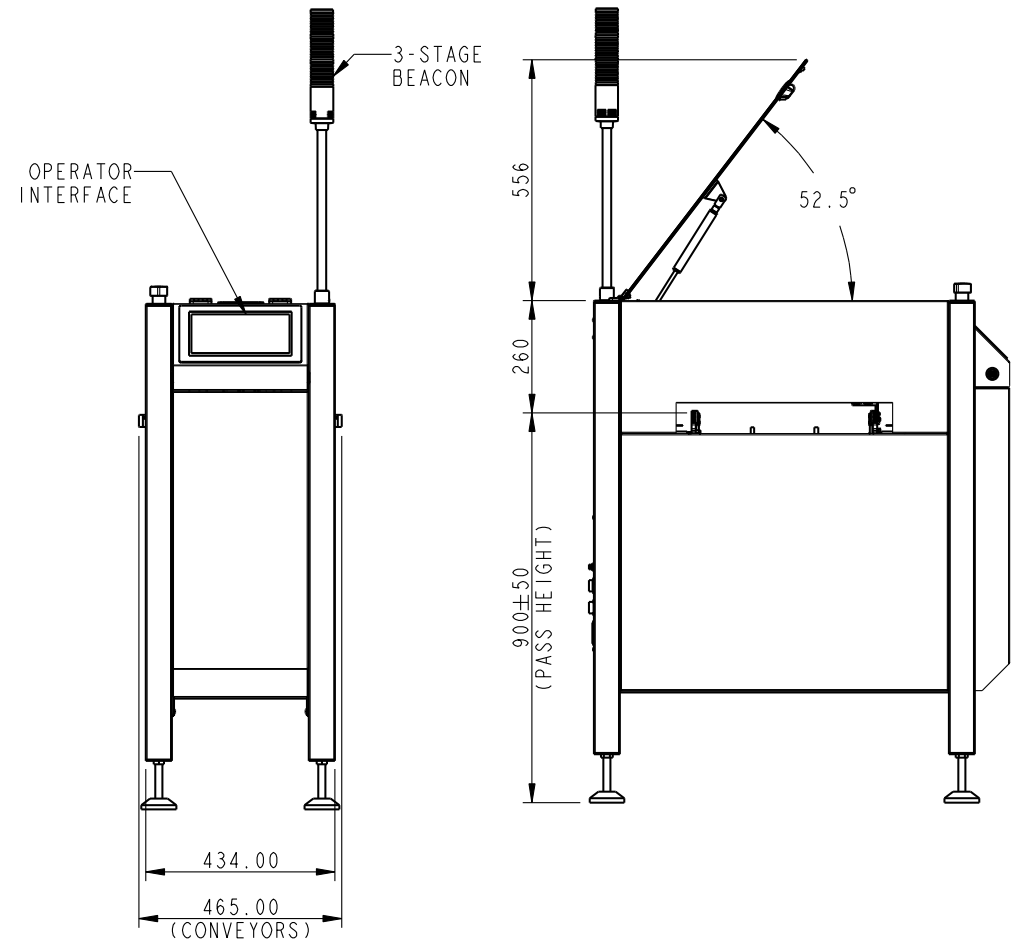
Product Compliance

Machine	ANSI / ESD s6.1 – 2019 & IEC 61340-5-1-2016
All Cleaning Rollers	ISO 6122 CLASS A
GNT / Nanoclean	ANSI / ESD s20.20 – 2014
All Adhesive	FINAT

Processing Capability

Cleaning Mode	
Min-Max Board Length	50-350mm
Min-Max Board Width	40-400mm
Min-Max Board Thickness	0.6-6mm
By-Pass Mode	
Min-Max Board Length	50-350mm
Min-Max Board Width	40-400mm
Min-Max Board Thickness	0.6-6mm

Note: "Long Board" option is available for boards longer than 350mm





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